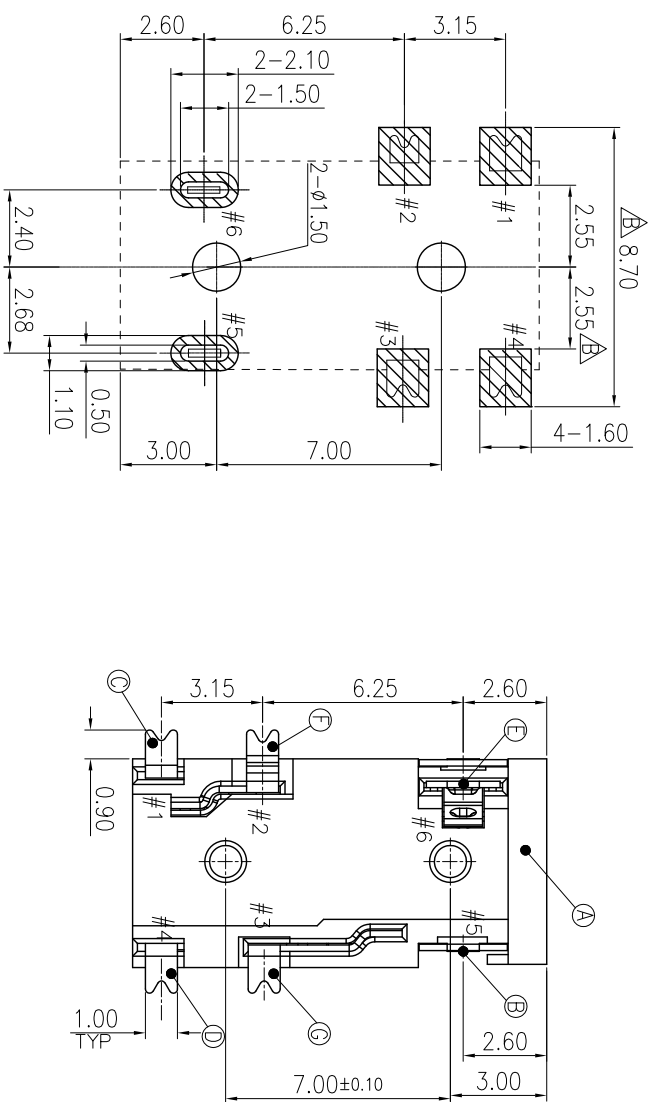
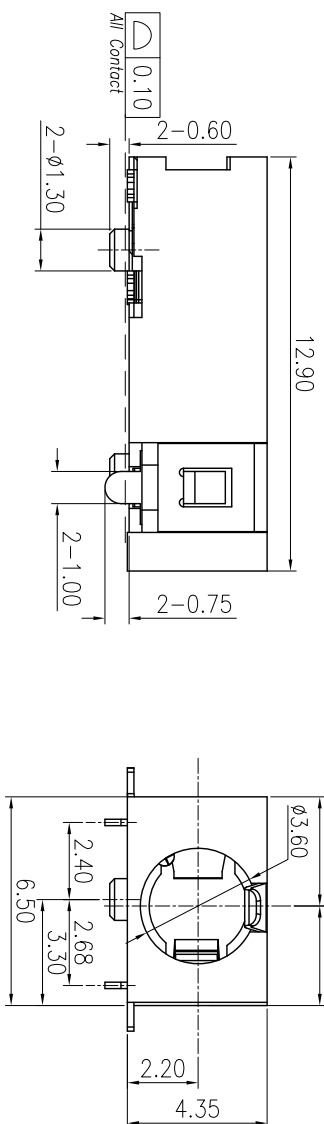
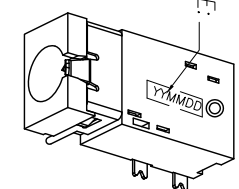
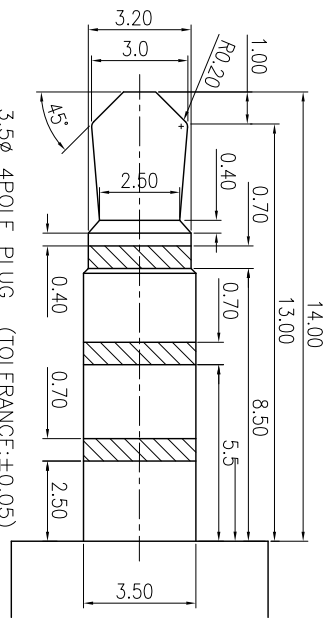
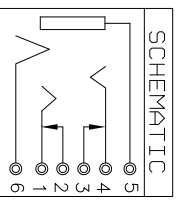


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PRODUCTS RELEASE	ARES	2010.09.16
B	ECN NO.C100448 MODIFY DIM	LONGJIANG	2010.12.13
C	ECN.C10387 Modify plating	LONGJIANG	2012.01.03



RECOMMENDED PCB LAYOUT  
TOP VIEW (TOLERANCE: ±0.05)



- SPECIFICATIONS:
- ELECTRICAL CHARACTERISTICS:
    - RATING : 12V /1A
    - CONTACT RESISTANCE: 30mMAX(INITIAL).
  - MECHANICAL CHARACTERISTICS:
    - INSERTION FORCE : 0.3~3.0 KGf
    - WITHDRAWAL FORCE : 0.3~3.0 KGf
    - LIFE TEST: 5,000 CYCLES .
    - TO CONFORM TO THE SINGATRON HSF SPECIFICATION.
    - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT.
    - HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING.
    - FOR REFLOW SOLDERING LEAD-FREE PROCESS.
    - SOLDER HEAT RESISTANCE REFLOW SOLDERING 260°C 10SECS.
    - PACKAGING: TAPE & REEL.

NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
A	BODY	1	HIGH TEMP.THERMOPLASTIC	BLACK
B	EARTH SPRING	1	COPPER ALLOY 0.2t	GOLD FLASH
C	TIP SPRING	1	COPPER ALLOY 0.2t	Gold flash on contact area And solder tail all over Nickel plated
D	RING SPRING-A	1	COPPER ALLOY 0.2t	GOLD FLASH
E	RING SPRING-B	1	COPPER ALLOY 0.2t	GOLD FLASH
F	SHUNT-A	1	COPPER ALLOY 0.2t	GOLD FLASH
G	SHUNT-B	1	COPPER ALLOY 0.2t	GOLD FLASH

UNLESS OTHERWISE SPECIFIED TOLERANCES

Singatron Enterprise Co., Ltd.  
信音企業股份有限公司

DECIMALS:	ANGLES:	TITLE	PART NO.	SCALE	UNIT:	SHEET:	REV:
X : ±0.5	X : ±2°	3.5mm 4POLE PHONE JACK	25J2269-102131F	4:1	mm	10F1	C
X.X : ±0.3	X.X : ±1°						
X.XX : ±0.2							

APVD 2012.01.09  
LMD 2012.01.09  
CUSTOMER COPY